

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Yoshikazu OSHIKA</td><td>02/22/2008</td></tr><tr><td>Masayuki NAKANO</td><td>02/22/2008</td></tr></tbody></table>	Name	Execution Date	Yoshikazu OSHIKA	02/22/2008	Masayuki NAKANO	02/22/2008					
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Masayuki NAKANO	02/22/2008										
RECEIVING PARTY DATA											
<table border="1"><tr><td>Name:</td><td>Dowa Electronics Materials Co., Ltd.</td></tr><tr><td>Street Address:</td><td>14-1, Sotokanda 4-chome, Chiyoda-ku</td></tr><tr><td>City:</td><td>Tokyo</td></tr><tr><td>State/Country:</td><td>JAPAN</td></tr><tr><td>Postal Code:</td><td>101-0021</td></tr></table>	Name:	Dowa Electronics Materials Co., Ltd.	Street Address:	14-1, Sotokanda 4-chome, Chiyoda-ku	City:	Tokyo	State/Country:	JAPAN	Postal Code:	101-0021	
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PROPERTY NUMBERS Total: 1											
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CORRESPONDENCE DATA											
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NAME OF SUBMITTER:	Masao Yoshimura										
Total Attachments: 1 source=US715DOW_assignment#page1.tif											

OP \$40.00 11908861

ASSIGNMENT

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:

SUBMOUNT AND METHOD OF MANUFACTURING THE SAME

for which I/WE executed an application for United States Letters Patent concurrently herewith; or filed an application for United States Letters Patent on September 17, 2007, (Application No. 11/ 908,861); and



WHEREAS, DOWA ELECTRONICS MATERIALS CO., LTD., a corporation in Japan, whose post office address is 14-1, Sotokanda 4-chome, Chiyoda-ku, Tokyo 101-0021, Japan, (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to issue upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/WE have empowered in the Declaration and Power of Attorney in this application, to insert here in parenthesis (Application No. _____, filed _____) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I/WE have hereunto set our hand(s).

Full Name of Sole or First Assignor Yoshikazu OSHIKA	Assignor's Signature 	Date February 22, 2008
Address c/o DOWA ELECTRONICS MATERIALS CO., LTD., 14-1, Sotokanda 4-chome, Chiyoda-ku, Tokyo 101-0021, Japan		Citizenship Japan
Full Name of Second Assignor Masayuki NAKANO	Assignor's Signature 	Date February 22, 2008
Address c/o DOWA ELECTRONICS MATERIALS CO., LTD., 14-1, Sotokanda 4-chome, Chiyoda-ku, Tokyo 101-0021, Japan		Citizenship Japan
Full Name of Third Assignor	Assignor's Signature	Date
Address		Citizenship
Names of additional inventors attached <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No		